

MC1413, MC1413B, NCV1413B



ON Semiconductor®

<http://onsemi.com>

High Voltage, High Current Darlington Transistor Arrays

The seven NPN Darlington connected transistors in these arrays are well suited for driving lamps, relays, or printer hammers in a variety of industrial and consumer applications. Their high breakdown voltage and internal suppression diodes insure freedom from problems associated with inductive loads. Peak inrush currents to 500 mA permit them to drive incandescent lamps.

The MC1413, B with a 2.7 kΩ series input resistor is well suited for systems utilizing a 5.0 V TTL or CMOS Logic.

Features

- Pb-Free Packages are Available*
- NCV Prefix for Automotive and Other Applications Requiring Site and Control Changes

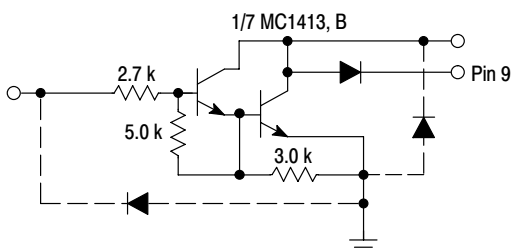


Figure 1. Representative Schematic Diagram

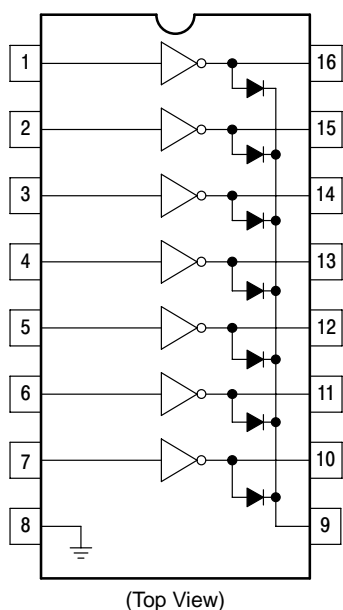
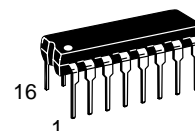
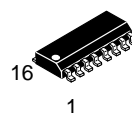


Figure 2. PIN CONNECTIONS



PDIP-16
P SUFFIX
CASE 648



SOIC-16
D SUFFIX
CASE 751B

ORDERING INFORMATION

Device	Package	Shipping†
MC1413D	SOIC-16	48 Units/Rail
MC1413DG	SOIC-16 (Pb-Free)	48 Units/Tube
MC1413DR2	SOIC-16	2500 Tape & Reel
MC1413DR2G	SOIC-16 (Pb-Free)	2500 Tape & Reel
MC1413P	PDIP-16	25 Units/Rail
MC1413PG	PDIP-16 (Pb-Free)	25 Units/Rail
MC1413BD	SOIC-16	48 Units/Rail
MC1413BDG	SOIC-16 (Pb-Free)	48 Units/Rail
MC1413BDR2	SOIC-16	2500 Tape & Reel
MC1413BDR2G	SOIC-16 (Pb-Free)	2500 Tape & Reel
MC1413BP	PDIP-16	25 Units/Rail
MC1413BPG	PDIP-16 (Pb-Free)	25 Units/Rail
NCV1413BDR2	SOIC-16	2500 Tape & Reel
NCV1413BDR2G	SOIC-16 (Pb-Free)	2500 Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 5 of this data sheet.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MC1413, MC1413B, NCV1413B

MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$, and rating apply to any one device in the package, unless otherwise noted.)

Rating	Symbol	Value	Unit
Output Voltage	V_O	50	V
Input Voltage	V_I	30	V
Collector Current – Continuous	I_C	500	mA
Base Current – Continuous	I_B	25	mA
Operating Ambient Temperature Range MC1413 MC1413B NCV1413B	T_A	-20 to +85 -40 to +85 -40 to +125	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-55 to +150	$^\circ\text{C}$
Junction Temperature	T_J	150	$^\circ\text{C}$
Thermal Resistance, Junction-to-Ambient Case 648, P Suffix Case 751B, D Suffix	$R_{\theta JA}$	67 100	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Case Case 648, P Suffix Case 751B, D Suffix	$R_{\theta JC}$	22 20	$^\circ\text{C}/\text{W}$
Electrostatic Discharge Sensitivity (ESD) Human Body Model (HBM) Machine Model (MM) Charged Device Model (CDM)	ESD	2000 400 1500	V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

MC1413, MC1413B, NCV1413B

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, unless otherwise noted)

Characteristic		Symbol	Min	Typ	Max	Unit
Output Leakage Current ($V_O = 50\text{ V}$, $T_A = +85^\circ\text{C}$) ($V_O = 50\text{ V}$, $T_A = +25^\circ\text{C}$)	All Types All Types	I_{CEX}	– –	– –	100 50	μA
Collector–Emitter Saturation Voltage ($I_C = 350\text{ mA}$, $I_B = 500\text{ }\mu\text{A}$) ($I_C = 200\text{ mA}$, $I_B = 350\text{ }\mu\text{A}$) ($I_C = 100\text{ mA}$, $I_B = 250\text{ }\mu\text{A}$)	All Types All Types All Types	$V_{CE(sat)}$	– – –	1.1 0.95 0.85	1.6 1.3 1.1	V
Input Current – On Condition ($V_I = 3.85\text{ V}$)	MC1413, B	$I_{I(on)}$	–	0.93	1.35	mA
Input Voltage – On Condition ($V_{CE} = 2.0\text{ V}$, $I_C = 200\text{ mA}$) ($V_{CE} = 2.0\text{ V}$, $I_C = 250\text{ mA}$) ($V_{CE} = 2.0\text{ V}$, $I_C = 300\text{ mA}$)	MC1413, B MC1413, B MC1413, B	$V_{I(on)}$	– – –	– – –	2.4 2.7 3.0	V
Input Current – Off Condition ($I_C = 500\text{ }\mu\text{A}$, $T_A = 85^\circ\text{C}$)	All Types	$I_{I(off)}$	50	100	–	μA
DC Current Gain ($V_{CE} = 2.0\text{ V}$, $I_C = 350\text{ mA}$)		h_{FE}	1000	–	–	–
Input Capacitance		C_I	–	15	30	pF
Turn–On Delay Time (50% E_I to 50% E_O)		t_{on}	–	0.25	1.0	μs
Turn–Off Delay Time (50% E_I to 50% E_O)		t_{off}	–	0.25	1.0	μs
Clamp Diode Leakage Current ($V_R = 50\text{ V}$)	$T_A = +25^\circ\text{C}$ $T_A = +85^\circ\text{C}$	I_R	– –	– –	50 100	μA
Clamp Diode Forward Voltage ($I_F = 350\text{ mA}$)		V_F	–	1.5	2.0	V

NOTE: NCV1413B $T_{low} = -40^\circ\text{C}$, $T_{high} = +125^\circ\text{C}$. Guaranteed by design. NCV prefix is for automotive and other applications requiring site and change control.

MC1413, MC1413B, NCV1413B

TYPICAL PERFORMANCE CURVES - $T_A = 25^\circ\text{C}$



Figure 3. Output Current versus Input Voltage



Figure 4. Output Current versus Input Current



Figure 5. Typical Output Characteristics



Figure 6. Input Characteristics - MC1413, B

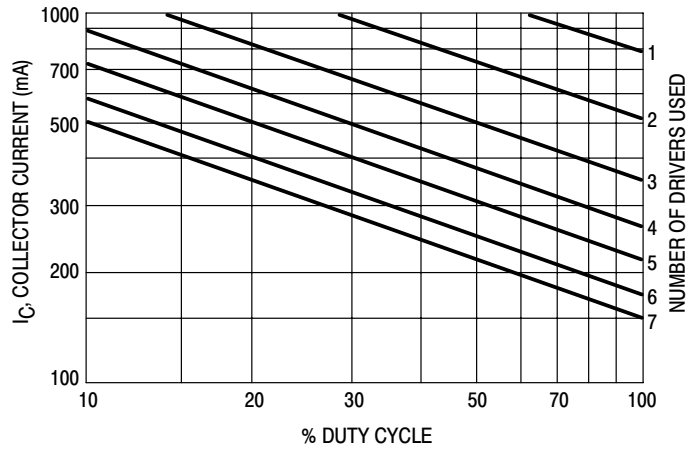
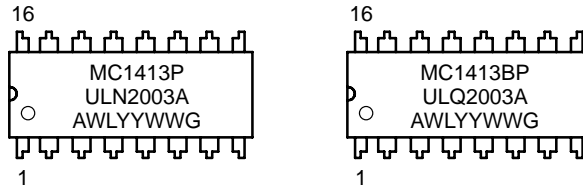


Figure 7. Maximum Collector Current versus Duty Cycle (and Number of Drivers in Use)

MC1413, MC1413B, NCV1413B

MARKING DIAGRAMS

PDIP-16 P SUFFIX CASE 648



SOIC-16 D SUFFIX CASE 751B



A = Assembly Location
WL = Wafer Lot
YY, Y = Year
WW = Work Week
G = Pb-Free Package

MECHANICAL CASE OUTLINE

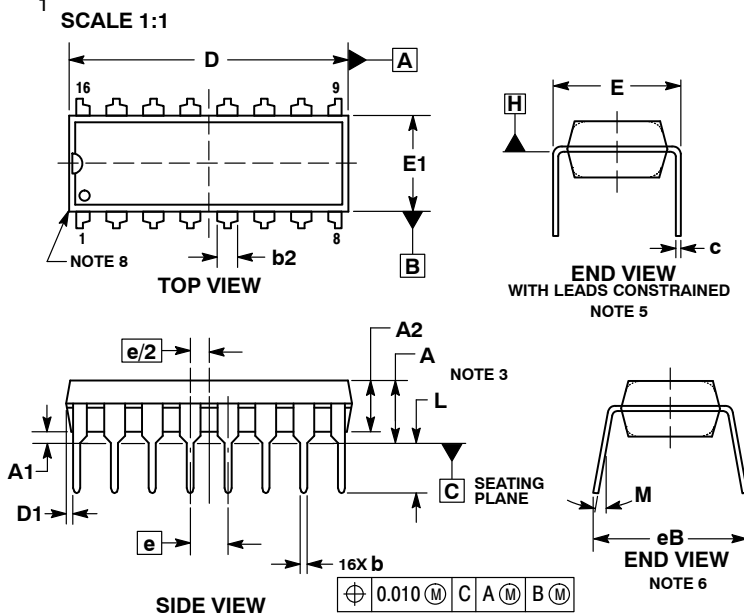
PACKAGE DIMENSIONS

ON Semiconductor®



PDIP-16 CASE 648-08 ISSUE V

DATE 22 APR 2015

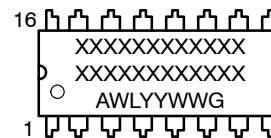


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES.
3. DIMENSIONS A, A1 AND L ARE MEASURED WITH THE PACKAGE SEATED IN JEDEC SEATING PLANE GAUGE GS-3.
4. DIMENSIONS D, D1 AND E1 DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS ARE NOT TO EXCEED 0.10 INCH.
5. DIMENSION E IS MEASURED AT A POINT 0.015 BELOW DATUM PLANE H WITH THE LEADS CONSTRAINED PERPENDICULAR TO DATUM C.
6. DIMENSION eB IS MEASURED AT THE LEAD TIPS WITH THE LEADS UNCONSTRAINED.
7. DATUM PLANE H IS COINCIDENT WITH THE BOTTOM OF THE LEADS, WHERE THE LEADS EXIT THE BODY.
8. PACKAGE CONTOUR IS OPTIONAL (ROUNDED OR SQUARE CORNERS).

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	---	0.210	---	5.33
A1	0.015	---	0.38	---
A2	0.115	0.195	2.92	4.95
b	0.014	0.022	0.35	0.56
b2	0.060 TYP		1.52 TYP	
C	0.008	0.014	0.20	0.36
D	0.735	0.775	18.67	19.69
D1	0.005	---	0.13	---
E	0.300	0.325	7.62	8.26
E1	0.240	0.280	6.10	7.11
e	0.100 BSC 2.54 BSC			
eB	---	0.430	---	10.92
L	0.115	0.150	2.92	3.81
M	---	10°	---	10°

GENERIC MARKING DIAGRAM*



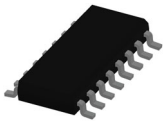
- XXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

- | | |
|----------------|---------------------|
| STYLE 1: | STYLE 2: |
| PIN 1. CATHODE | PIN 1. COMMON DRAIN |
| 2. CATHODE | 2. COMMON DRAIN |
| 3. CATHODE | 3. COMMON DRAIN |
| 4. CATHODE | 4. COMMON DRAIN |
| 5. CATHODE | 5. COMMON DRAIN |
| 6. CATHODE | 6. COMMON DRAIN |
| 7. CATHODE | 7. COMMON DRAIN |
| 8. CATHODE | 8. COMMON DRAIN |
| 9. ANODE | 9. GATE |
| 10. ANODE | 10. SOURCE |
| 11. ANODE | 11. GATE |
| 12. ANODE | 12. SOURCE |
| 13. ANODE | 13. GATE |
| 14. ANODE | 14. SOURCE |
| 15. ANODE | 15. GATE |
| 16. ANODE | 16. SOURCE |

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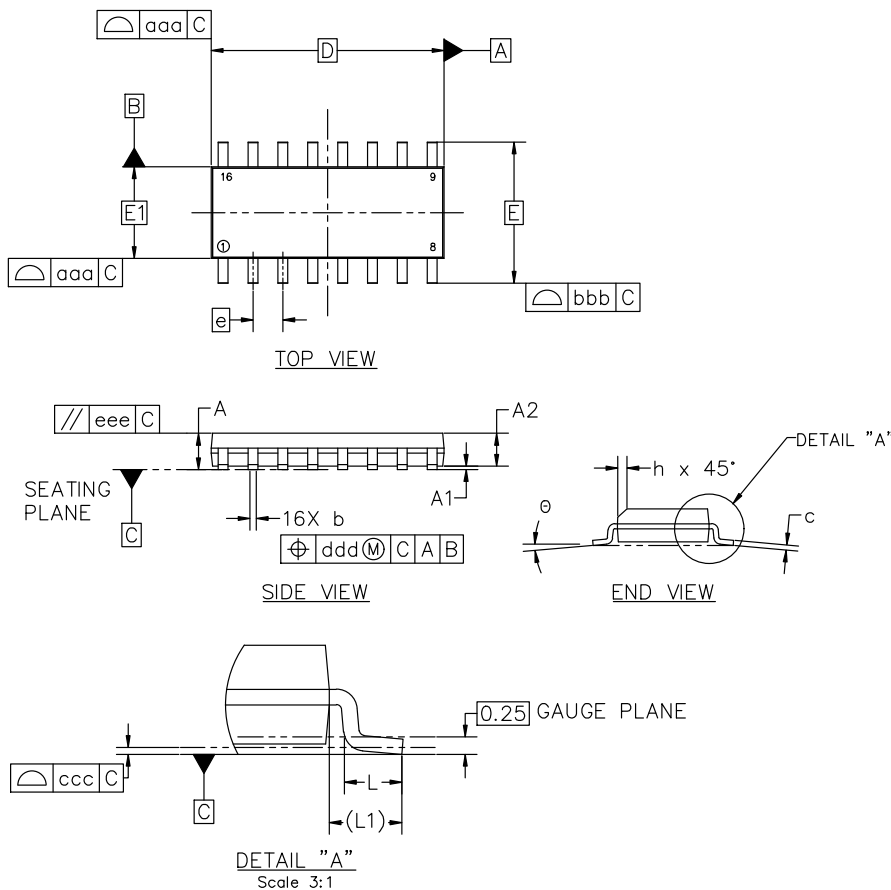


SOIC-16 9.90x3.90x1.50 1.27P
CASE 751B
ISSUE L

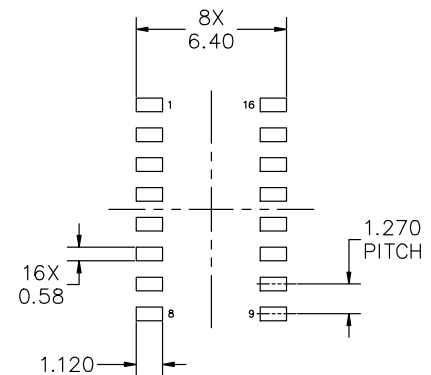
DATE 29 MAY 2024

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
2. DIMENSION IN MILLIMETERS. ANGLE IN DEGREES.
3. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15mm PER SIDE.
5. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127mm TOTAL IN EXCESS OF THE b DIMENSION AT MAXIMUM MATERIAL CONDITION.



MILLIMETERS			
DIM	MIN	NOM	MAX
A	1.35	1.55	1.75
A1	0.00	0.05	0.10
A2	1.35	1.50	1.65
b	0.35	0.42	0.49
c	0.19	0.22	0.25
D	9.90 BSC		
E	6.00 BSC		
E1	3.90 BSC		
e	1.27 BSC		
h	0.25	---	0.50
L	0.40	0.83	1.25
L1	1.05 REF		
θ	0°	---	7°
TOLERANCE OF FORM AND POSITION			
aaa	0.10		
bbb	0.20		
ccc	0.10		
ddd	0.25		
eee	0.10		



RECOMMENDED MOUNTING FOOTPRINT

*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE onsemi SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D

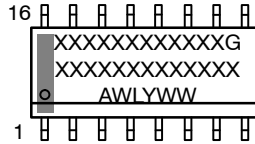
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SOIC-16 9.90x3.90x1.50 1.27P
CASE 751B
ISSUE L

DATE 29 MAY 2024

GENERIC
MARKING DIAGRAM*



XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
Y = Year
WW = Work Week
G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

<p>STYLE 1:</p> <p>PIN 1. COLLECTOR</p> <p>2. BASE</p> <p>3. EMITTER</p> <p>4. NO CONNECTION</p> <p>5. EMITTER</p> <p>6. BASE</p> <p>7. COLLECTOR</p> <p>8. COLLECTOR</p> <p>9. BASE</p> <p>10. EMITTER</p> <p>11. NO CONNECTION</p> <p>12. EMITTER</p> <p>13. BASE</p> <p>14. COLLECTOR</p> <p>15. EMITTER</p> <p>16. COLLECTOR</p>	<p>STYLE 2:</p> <p>PIN 1. CATHODE</p> <p>2. ANODE</p> <p>3. NO CONNECTION</p> <p>4. CATHODE</p> <p>5. CATHODE</p> <p>6. NO CONNECTION</p> <p>7. ANODE</p> <p>8. CATHODE</p> <p>9. CATHODE</p> <p>10. ANODE</p> <p>11. NO CONNECTION</p> <p>12. CATHODE</p> <p>13. CATHODE</p> <p>14. NO CONNECTION</p> <p>15. ANODE</p> <p>16. CATHODE</p>	<p>STYLE 3:</p> <p>PIN 1. COLLECTOR, DYE #1</p> <p>2. BASE, #1</p> <p>3. EMITTER, #1</p> <p>4. COLLECTOR, #1</p> <p>5. COLLECTOR, #2</p> <p>6. BASE, #2</p> <p>7. EMITTER, #2</p> <p>8. COLLECTOR, #2</p> <p>9. COLLECTOR, #3</p> <p>10. BASE, #3</p> <p>11. EMITTER, #3</p> <p>12. COLLECTOR, #3</p> <p>13. COLLECTOR, #4</p> <p>14. BASE, #4</p> <p>15. EMITTER, #4</p> <p>16. COLLECTOR, #4</p>	<p>STYLE 4:</p> <p>PIN 1. COLLECTOR, DYE #1</p> <p>2. COLLECTOR, #1</p> <p>3. COLLECTOR, #2</p> <p>4. COLLECTOR, #2</p> <p>5. COLLECTOR, #3</p> <p>6. COLLECTOR, #3</p> <p>7. COLLECTOR, #4</p> <p>8. COLLECTOR, #4</p> <p>9. BASE, #4</p> <p>10. EMITTER, #4</p> <p>11. BASE, #3</p> <p>12. EMITTER, #3</p> <p>13. BASE, #2</p> <p>14. EMITTER, #2</p> <p>15. BASE, #1</p> <p>16. EMITTER, #1</p>
<p>STYLE 5:</p> <p>PIN 1. DRAIN, DYE #1</p> <p>2. DRAIN, #1</p> <p>3. DRAIN, #2</p> <p>4. DRAIN, #2</p> <p>5. DRAIN, #3</p> <p>6. DRAIN, #3</p> <p>7. DRAIN, #4</p> <p>8. DRAIN, #4</p> <p>9. GATE, #4</p> <p>10. SOURCE, #4</p> <p>11. GATE, #3</p> <p>12. SOURCE, #3</p> <p>13. GATE, #2</p> <p>14. SOURCE, #2</p> <p>15. GATE, #1</p> <p>16. SOURCE, #1</p>	<p>STYLE 6:</p> <p>PIN 1. CATHODE</p> <p>2. CATHODE</p> <p>3. CATHODE</p> <p>4. CATHODE</p> <p>5. CATHODE</p> <p>6. CATHODE</p> <p>7. CATHODE</p> <p>8. CATHODE</p> <p>9. ANODE</p> <p>10. ANODE</p> <p>11. ANODE</p> <p>12. ANODE</p> <p>13. ANODE</p> <p>14. ANODE</p> <p>15. ANODE</p> <p>16. ANODE</p>	<p>STYLE 7:</p> <p>PIN 1. SOURCE N-CH</p> <p>2. COMMON DRAIN (OUTPUT)</p> <p>3. COMMON DRAIN (OUTPUT)</p> <p>4. GATE P-CH</p> <p>5. COMMON DRAIN (OUTPUT)</p> <p>6. COMMON DRAIN (OUTPUT)</p> <p>7. COMMON DRAIN (OUTPUT)</p> <p>8. SOURCE P-CH</p> <p>9. SOURCE P-CH</p> <p>10. COMMON DRAIN (OUTPUT)</p> <p>11. COMMON DRAIN (OUTPUT)</p> <p>12. COMMON DRAIN (OUTPUT)</p> <p>13. GATE N-CH</p> <p>14. COMMON DRAIN (OUTPUT)</p> <p>15. COMMON DRAIN (OUTPUT)</p> <p>16. SOURCE N-CH</p>	

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